

PC716V0NSZX/ PC716V0YSZX

■ Features

1. High collector current (I_C :MAX. 200mA)
2. High sensitivity (CTR:MIN. 1 000%)
3. Isolation voltage (Viso (rms):5kV)
4. Recognized by UL, file No.E64380
Approved by TÜV (VDE0884)(PC716V0YSZX)
5. 6-pin DIP package

■ Applications

1. Home appliances
2. Programmable controllers
3. Peripheral equipment of personal computers

■ Model Line-up

Model No.	* Safty Standard Approval	
	UL	TÜV(VDE0884)
PC716V0NSZX	○	—
PC716V0YSZX	○	○

* Application Model No. PC716V

■ Absolute Maximum Ratings (Ta=25°C)

	Parameter	Symbol	Rating	Unit
Input	Forward current	I_F	50	mA
	*1 Peak forward current	I_{FM}	1	A
	Reverse voltage	V_R	6	V
	Power dissipation	P	70	mW
Output	Collector-emitter voltage	V_{CEO}	35	V
	Emitter-collector voltage	V_{ECO}	6	V
	Collector current	I_C	200	mA
	Collector power dissipation	P_C	300	mW
	Total power dissipation	P_{tot}	350	mW
	*2 Isolation voltage	V_{iso} (rms)	5	kV
	Operating temperature	T_{opr}	-25 to +100	°C
	Storage temperature	T_{stg}	-40 to +125	°C
	*3 Soldering temperature	T_{sol}	260	°C

*1 Pulse width≤100μs, Duty ratio=0.001

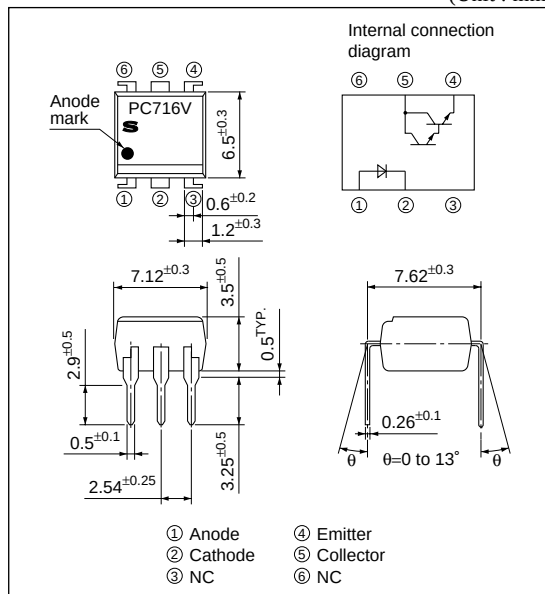
*2 40 to 60%RH, AC for 1 min

*3 For 10 s

High Sensitivity and High Collector Current Type Photocoupler

■ Outline Dimensions

(Unit : mm)



■ Electro-optical Characteristics

(Ta=25°C)

Parameter			Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage		V _F	I _F =10mA	—	1.2	1.4	V
	Peak forward voltage		V _{FM}	I _{FM} =0.5A	—	—	3.0	V
	Reverse current		I _R	V _R =4V	—	—	10	μA
	Terminal capacitance		C _t	V=0, f=1kHz	—	30	250	pF
Output	Collector dark current		I _{CEO}	V _{CE} =10V, I _F =0	—	—	10 ⁻⁶	A
Transfer charac- teristics	Collector current		I _C	I _F =1mA, V _{CE} =2V	10	60	150	mA
	Collector-emitter saturation voltage		V _{CE(sat)}	I _F =20mA, I _C =10mA	—	—	1.2	V
	Isolation resistance		R _{ISO}	DC500V, 40 to 60%RH	5×10 ¹⁰	10 ¹¹	—	Ω
	Floating capacitance		C _f	V=0, f=1MHz	—	0.6	1.0	pF
	Cut-off frequency		f _c	V _{CE} =2V, I _C =10mA, R _L =100Ω, -3dB	—	3	—	kHz
	Response time	Rise time	t _r	V _{CE} =2V, I _C =20mA R _L =100Ω	—	130	400	μs
Fall time		t _f	—		60	350	μs	

Fig.1 Forward Current vs. Ambient Temperature

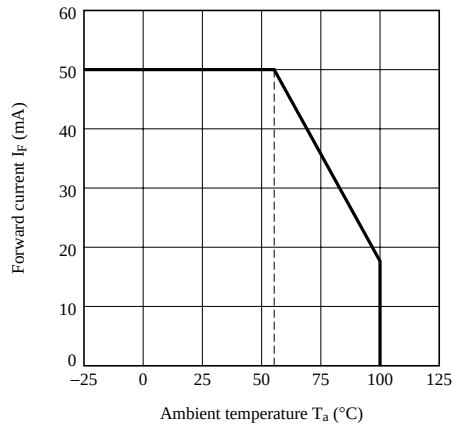


Fig.2 Collector Power Dissipation vs. Ambient Temperature

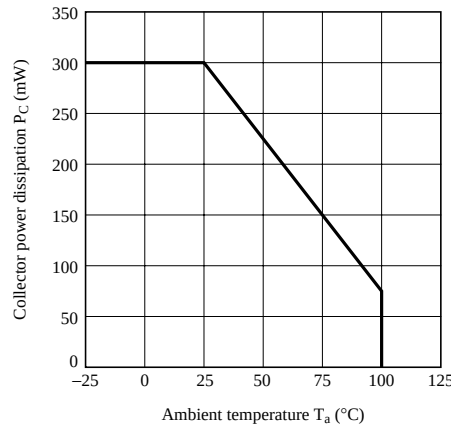


Fig.3 Peak Forward Current vs. Duty Ratio

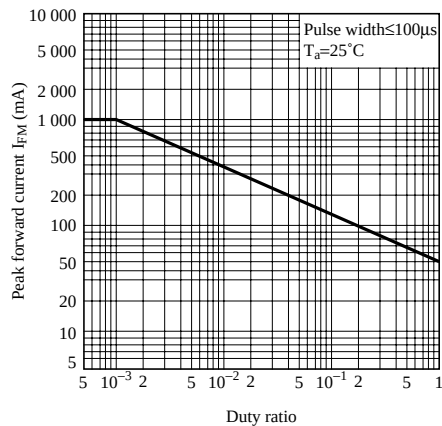


Fig.4 Forward Current vs. Forward Voltage

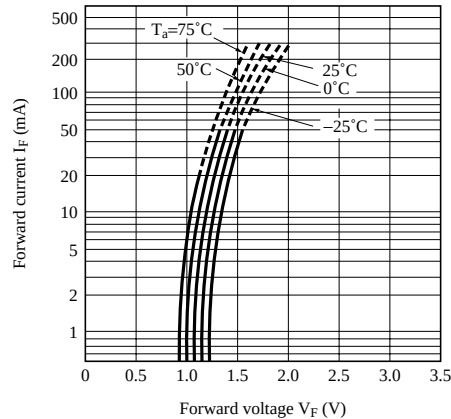


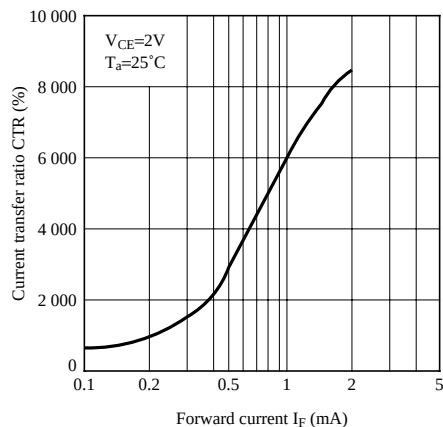
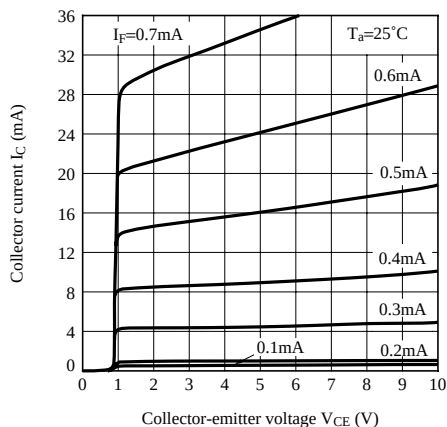
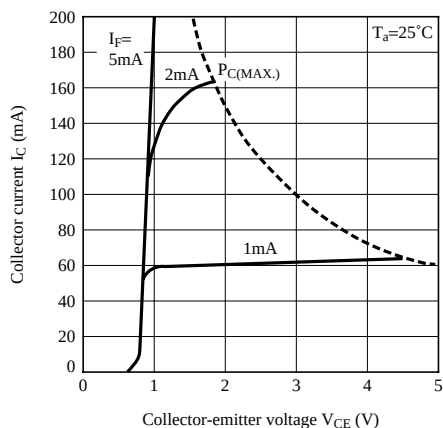
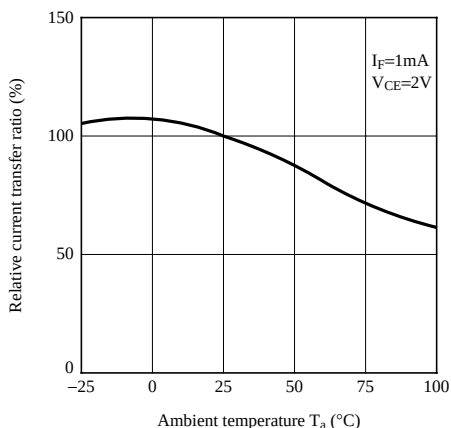
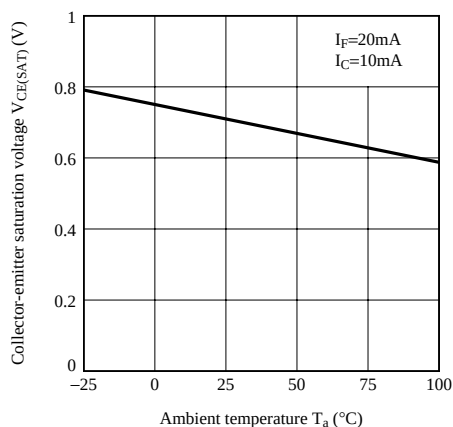
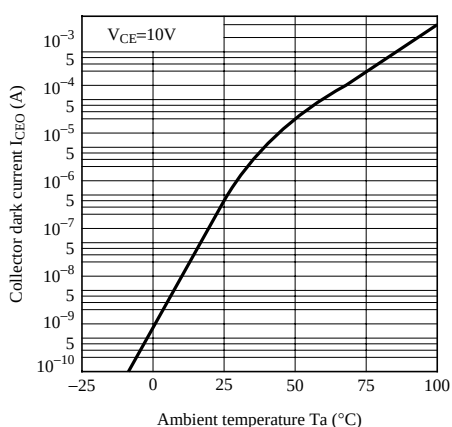
Fig.5 Current Transfer Ratio vs. Forward Current**Fig.6 Collector Current vs. Collector-emitter Voltage****Fig.7 Collector Current vs. Collector-emitter Voltage****Fig.8 Relative Current Transfer Ratio vs. Ambient Temperature****Fig.9 Collector - emitter Saturation Voltage vs. Ambient Temperature****Fig.10 Collector Dark Current vs. Ambient Temperature**

Fig.11 Response Time vs. Load Resistance

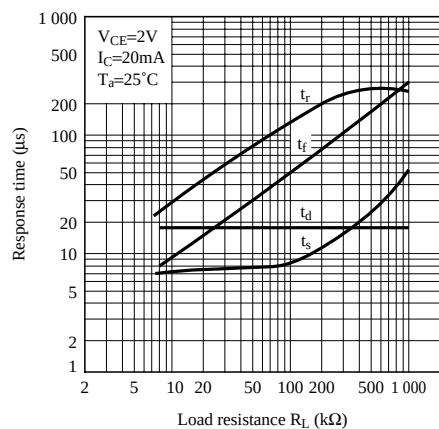


Fig.12 Test Circuit for Response Time

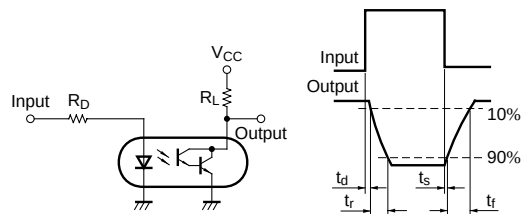


Fig.13 Frequency Response

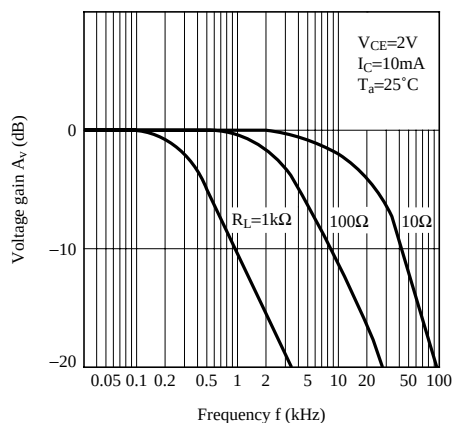
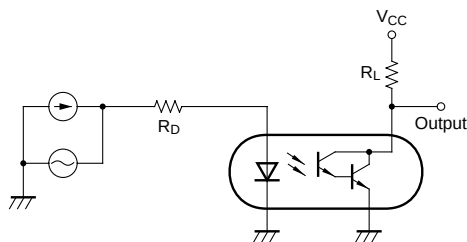


Fig.14 Test Circuit for Frequency Response



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